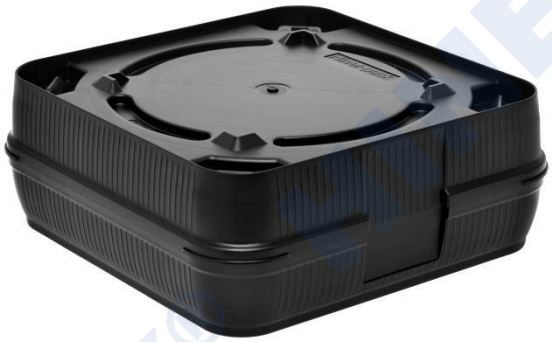
Hiner-pack® MHWS Canister 200 mm

Designed for secure wafer transport and storage in semiconductor manufacturing processes



As semiconductor technology advances, manufacturers are increasingly using thinner and more delicate wafers, especially in consumer electronics. These ultrathin wafers pose significant handling and transport challenges due to their sensitivity to breakage, warping, and contamination. The 200 mm clamp ring wafer shipper from Hiner-pack® is specifically designed to meet these demands, offering secure storage and transportation for up to 25 wafers of varying thicknesses. Made from high-performance, engineering-grade polymer, the shipper eliminates the need for traditional ESD interleaf like Tyvek® paper and PE film by using individual clamp rings to reduce surface contact and contamination risks. This innovative design minimizes wafer movement, protects edge and surface integrity, and ensures wafers arrive in optimal condition. This clamp ring shipper is ideal for fabs seeking to improve wafer handling efficiency while maintaining cleanliness and reducing damage.

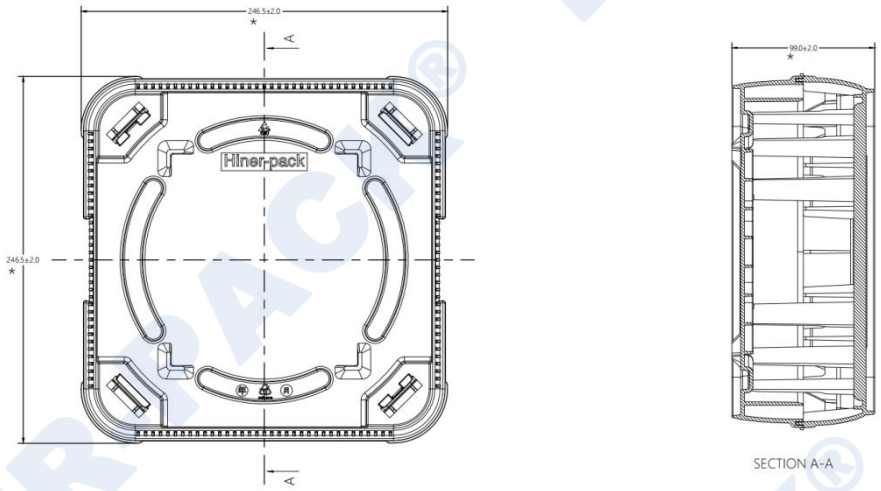
SPECIFICATIONS

- 246.5 mm L × 246.5 mm W × 99 mm H (9.7" × 9.7" × 3.9")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (10)

FEATURES & BENEFITS

- Individual clamp rings design protects wafers from shock and edge damage
- ESD-safe, engineering-grade polymer resists ionic contamination and particle generation
- Contactless wafer support avoids surface contact, ideal for thinned or bumped wafers
- Automation interface compatible with wafer handling systems
- Stackable, reusable for cost-efficient shipping

DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MHWS-8/25-203/70	Bottom+Cushion+Clamp Ring+Top	200 mm

REFERENCE ILLUSTRATION

The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183-1 (23°C)	1.0 g/cm³
Melt Index (350°C/5kg)	ASTM D–1238	15.0 g/10min
Shrinkage Percentage	ISO 2577	1.2~1.6 %
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Strength (Fracture)	ISO 178 (2mm/min)	27 MPa
Flexural Modulus	ISO 178 (2mm/min)	1150 MPa
LZOD Notch Impact Strength (3.2mm)	ISO 180 (23°C)	30 kJ/m²
Surface Resistivity	ASTM D–257	1.0×10^{4}~1.0×10^{9} Ω/sq
Flame Retardant Rating	UL 94	HB Class

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.

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